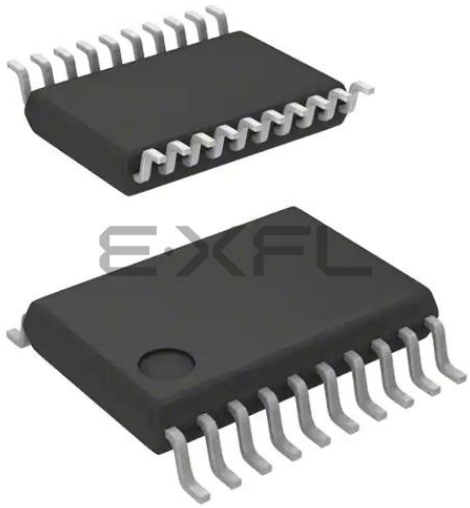

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Applications of "Embedded - Microcontrollers"

Details	
Product Status	Obsolete
Core Processor	R8C
Core Size	16-Bit
Speed	20MHz
Connectivity	SIO, SSU, UART/USART
Peripherals	LED, POR, Voltage Detect, WDT
Number of I/O	13
Program Memory Size	16KB (16K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	1K x 8
Voltage - Supply (Vcc/Vdd)	2.7V ~ 5.5V
Data Converters	A/D 4x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	20-LSSOP (0.173", 4.40mm Width)
Supplier Device Package	20-LSSOP
Purchase URL	https://www.e-xfl.com/product-detail/renesas-electronics-america/r5f21154dsp-u0

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Table 1.2 Performance Outline of the R8C/15 Group

Item		Performance
CPU	Number of Basic Instructions	89 instructions
	Minimum Instruction Execution Time	50ns (f(XIN)=20MHz, VCC=3.0 to 5.5V) 100ns (f(XIN)=10MHz, VCC=2.7 to 5.5V)
	Operating Mode	Single-chip
	Memory Space	1 Mbyte
	Memory Capacity	See **Table 1.4 R8C/15 Group Product Information**
Peripheral Function	Port	I/O : 13 pins (including LED drive port), Input : 2 pins
	LED drive port	I/O port: 4 pins
	Timer	Timer X: 8 bits × 1 channel, Timer Z: 8 bits × 1 channel (Each timer equipped with 8-bit prescaler) Timer C: 16 bits × 1 channel (Circuits of input capture and output compare)
	Serial Interface	1 channel Clock synchronous serial I/O, UART
	Chip-select clock synchronous serial I/O (SSU)	1 channel
	A/D Converter	10-bit A/D converter: 1 circuit, 4 channels
	Watchdog Timer	15 bits × 1 channel (with prescaler) Reset start selectable, Count source protection mode
	Interrupt	Internal: 9 factors, External: 4 factors, Software: 4 factors Priority level: 7 levels
	Clock Generation Circuit	2 circuits • Main clock generation circuit (Equipped with a built-in feedback resistor) • On-chip oscillator (high speed, low speed) Equipped with frequency adjustment function on high-speed on-chip oscillator
	Oscillation Stop Detection Function	Main clock oscillation stop detection function
	Voltage Detection Circuit	Included

1.4 Product Information

Table 1.3 lists the Product Information of R8C/14 Group and Table 1.4 lists the Product Information of R8C/15 Group.

Table 1.3 Product Information of R8C/14 Group **As of Jan 2006**

Type No.	ROM capacity	RAM capacity	Package type	Remarks
R5F21142SP	8 Kbytes	512 bytes	PLSP0020JB-A	Flash memory version
R5F21143SP	12 Kbytes	768 bytes	PLSP0020JB-A	
R5F21144SP	16 Kbytes	1 Kbyte	PLSP0020JB-A	
R5F21142DSP	8 Kbytes	512 bytes	PLSP0020JB-A	D version
R5F21143DSP	12 Kbytes	768 bytes	PLSP0020JB-A	
R5F21144DSP	16 Kbytes	1 Kbyte	PLSP0020JB-A	

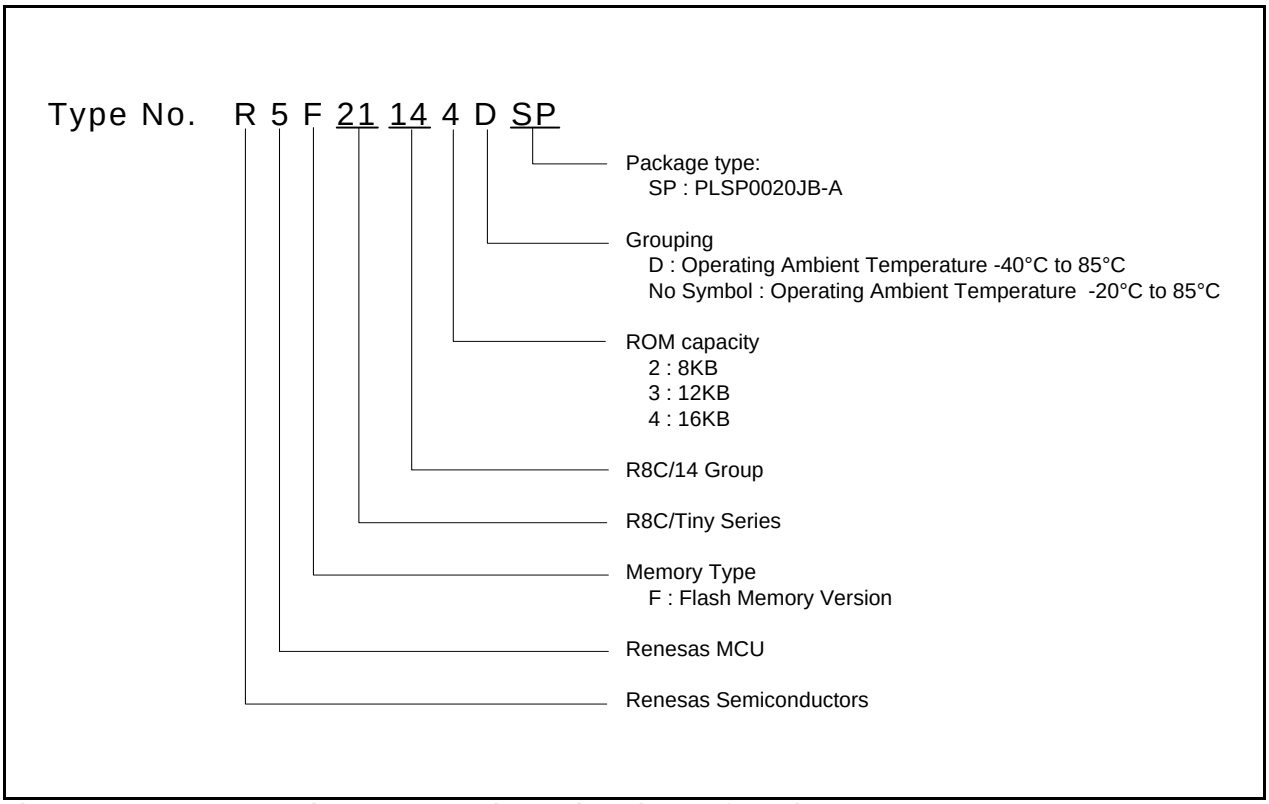


Figure 1.2 Part Number, Memory Size and Package of R8C/14 Group

1.6 Pin Description

Table 1.5 lists the Pin Description and Table 1.6 lists the Pin Name Information by Pin Number.

Table 1.5 Pin Description

Function	Pin name	I/O type	Description
Power Supply Input	VCC VSS	I	Apply 2.7V to 5.5V to the VCC pin. Apply 0V to the VSS pin
Analog Power Supply Input	AVCC AVSS	I	Power supply input pins to A/D converter. Connect AVCC to VCC. Apply 0V to AVSS. Connect a capacitor between AVCC and AVSS.
Reset Input	$\overline{\text{RESET}}$	I	Input “L” on this pin resets the MCU
MODE	MODE	I	Connect this pin to VCC via a resistor
Main Clock Input	XIN	I	These pins are provided for the main clock generation circuit I/O. Connect a ceramic resonator or a crystal oscillator between the XIN and XOUT pins. To use an externally derived clock, input it to the XIN pin and leave the XOUT pin open.
Main Clock Output	XOUT	O	
$\overline{\text{INT}}$ Interrupt	$\overline{\text{INT0}}$, $\overline{\text{INT1}}$, $\overline{\text{INT3}}$	I	INT interrupt input pins
Key Input Interrupt	$\overline{\text{KI0}}$ to $\overline{\text{KI3}}$	I	Key input interrupt input pins
Timer X	CNTR0	I/O	Timer X I/O pin
	$\overline{\text{CNTR0}}$	O	Timer X output pin.
Timer Z	TZOUT	O	Timer Z output pin
Timer C	TCIN	I	Timer C input pin
	CMP0_0 to CMP0_2, CMP1_0 to CMP1_2	O	Timer C output pins.
Serial Interface	CLK0	I/O	Transfer clock I/O pin.
	RXD0	I	Serial data input pin.
	TXD0	O	Serial data output pin.
SSU	SSI	I/O	Data I/O pin.
	$\overline{\text{SCS}}$	I/O	Chip-select signal I/O pin.
	SSCK	I/O	Clock I/O pin.
	SSO	I/O	Data I/O pin.
Reference Voltage Input	VREF	I	Reference voltage input pin to A/D converter Connect VREF to VCC
A/D Converter	AN8 to AN11	I	Analog input pins to A/D converter
I/O Port	P1_0 to P1_7, P3_3 to P3_5, P3_7, P4_5	I/O	These are CMOS I/O ports. Each port contains an I/O select direction register, allowing each pin in that port to be directed for input or output individually. Any port set to input can select whether to use a pull-up resistor or not by program. P1_0 to P1_3 also function as LED drive ports.
Input Port	P4_6, P4_7	I	Port for input-only

I: Input O: Output I/O: Input and output

2.1 Data Registers (R0, R1, R2 and R3)

R0 is a 16-bit register for transfer, arithmetic and logic operations. The same applies to R1 to R3. The R0 can be split into high-order bit (R0H) and low-order bit (R0L) to be used separately as 8-bit data registers. The same applies to R1H and R1L as R0H and R0L. R2 can be combined with R0 to be used as a 32-bit data register (R2R0). The same applies to R3R1 as R2R0.

2.2 Address Registers (A0 and A1)

A0 is a 16-bit register for address register indirect addressing and address register relative addressing. They also are used for transfer, arithmetic and logic operations. The same applies to A1 as A0. A0 can be combined with A0 to be used as a 32-bit address register (A1A0).

2.3 Frame Base Register (FB)

FB is a 16-bit register for FB relative addressing.

2.4 Interrupt Table Register (INTB)

INTB is a 20-bit register indicates the start address of an interrupt vector table.

2.5 Program Counter (PC)

PC, 20 bits wide, indicates the address of an instruction to be executed.

2.6 User Stack Pointer (USP) and Interrupt Stack Pointer (ISP)

The stack pointer (SP), USP and ISP, are 16 bits wide each. The U flag of FLG is used to switch between USP and ISP.

2.7 Static Base Register (SB)

SB is a 16-bit register for SB relative addressing.

2.8 Flag Register (FLG)

FLG is a 11-bit register indicating the CPU state.

2.8.1 Carry Flag (C)

The C flag retains a carry, borrow, or shift-out bit that has occurred in the arithmetic logic unit.

2.8.2 Debug Flag (D)

The D flag is for debug only. Set to “0”.

2.8.3 Zero Flag (Z)

The Z flag is set to “1” when an arithmetic operation resulted in 0; otherwise, “0”.

2.8.4 Sign Flag (S)

The S flag is set to “1” when an arithmetic operation resulted in a negative value; otherwise, “0”.

2.8.5 Register Bank Select Flag (B)

The register bank 0 is selected when the B flag is “0”. The register bank 1 is selected when this flag is set to “1”.

2.8.6 Overflow Flag (O)

The O flag is set to “1” when the operation resulted in an overflow; otherwise, “0”.

2.8.7 Interrupt Enable Flag (I Flag)

The I flag enables a maskable interrupt.
An interrupt is disabled when the I flag is set to “0”, and are enabled when the I flag is set to “1”. The I flag is set to “0” when an interrupt request is acknowledged.

2.8.8 Stack Pointer Select Flag (U Flag)

ISP is selected when the U flag is set to “0”, USP is selected when the U flag is set to “1”.
The U flag is set to “0” when a hardware interrupt request is acknowledged or the INT instruction of software interrupt numbers 0 to 31 is executed.

2.8.9 Processor Interrupt Priority Level (IPL)

IPL, 3 bits wide, assigns processor interrupt priority levels from level 0 to level 7.
If a requested interrupt has greater priority than IPL, the interrupt is enabled.

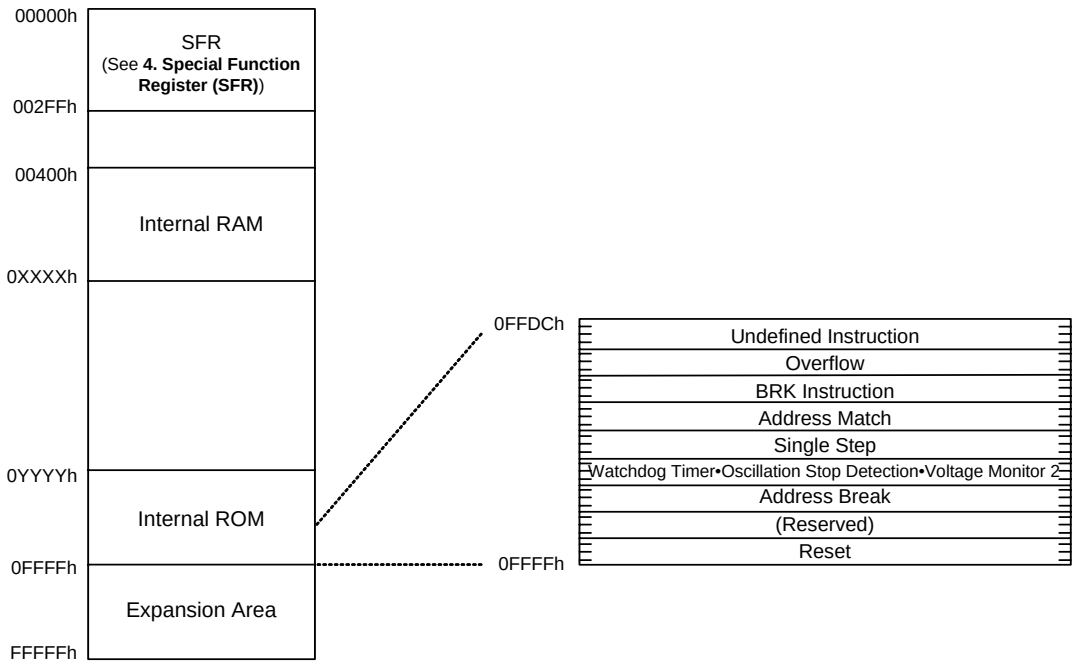
2.8.10 Reserved Bit

When write to this bit, set to “0”. When read, its content is indeterminate.

3. Memory

3.1 R8C/14 Group

Figure 3.1 is a Memory Map of R8C/14 Group. The R8C/14 group provides 1-Mbyte address space from addresses 00000h to FFFFFh.
The internal ROM is allocated lower addresses beginning with address 0FFFFh. For example, a 16-Kbyte internal ROM is allocated addresses 0C000h to 0FFFFh.
The fixed interrupt vector table is allocated addresses 0FFDCh to 0FFFFh. They store the starting address of each interrupt routine.
The internal RAM is allocated higher addresses beginning with address 00400h. For example, a 1-Kbyte internal RAM is allocated addresses 00400h to 007FFh. The internal RAM is used not only for storing data but for calling subroutines and stacks when interrupt request is acknowledged.
Special function registers (SFR) are allocated addresses 00000h to 002FFh. The peripheral function control registers are allocated them. All addresses, which have nothing allocated within the SFR, are reserved area and cannot be accessed by users.



NOTES:
1. Blank spaces are reserved. No access is allowed.

Part Number	Internal ROM		Internal RAM	
	Size	0YYYYh	Size	0XXXXh
R5F21144SP, R5F21144DSP	16 Kbytes	0C000h	1 Kbytes	007FFh
R5F21143SP, R5F21143DSP	12 Kbytes	0D000h	768 bytes	006FFh
R5F21142SP, R5F21142DSP	8 Kbytes	0E000h	512 bytes	005FFh

Figure 3.1 Memory Map of R8C/14 Group

Table 4.4 SFR Information(4)(1)

Address	Register	Symbol	After reset
00C0h	A/D Register	AD	XXh
00C1h			XXh
00C2h			
00C3h			
00C4h			
00C5h			
00C6h			
00C7h			
00C8h			
00C9h			
00CAh			
00CBh			
00CCh			
00CDh			
00CEh			
00CFh			
00D0h			
00D1h			
00D2h			
00D3h			
00D4h	A/D Control Register 2	ADCON2	00h
00D5h			
00D6h	A/D Control Register 0	ADCON0	00000XXXb
00D7h	A/D Control Register 1	ADCON1	00h
00D8h			
00D9h			
00DAh			
00DBh			
00DCh			
00DDh			
00DEh			
00DFh			
00E0h			
00E1h	Port P1 Register	P1	XXh
00E2h			
00E3h	Port P1 Direction Register	PD1	00h
00E4h			
00E5h	Port P3 Register	P3	XXh
00E6h			
00E7h	Port P3 Direction Register	PD3	00h
00E8h	Port P4 Register	P4	XXh
00E9h			
00EAh	Port P4 Direction Register	PD4	00h
00EBh			
00ECh			
00EDh			
00EEh			
00EFh			
00F0h			
00F1h			
00F2h			
00F3h			
00F4h			
00F5h			
00F6h			
00F7h			
00F8h			
00F9h			
00FAh			
00FBh			
00FCh	Pull-Up Control Register 0	PUR0	00XX0000b
00FDh	Pull-Up Control Register 1	PUR1	XXXXXX0Xb
00FEh	Port P1 Drive Capacity Control Register	DRR	00h
00FFh	Timer C Output Control Register	TCOUT	00h
01B3h	Flash Memory Control Register 4	FMR4	01000000b
01B4h			
01B5h	Flash Memory Control Register 1	FMR1	1000000Xb
01B6h			
01B7h	Flash Memory Control Register 0	FMR0	00000001b
0FFFFh	Optional Function Select Register	OFS	(2)

X: Undefined

NOTES:

1. Blank columns, 0100h to 01B2h and 01B8h to 02FFh are all reserved. No access is allowed.
2. The OFS register cannot be changed by program. Use a flash programmer to write to it.

5. Electrical Characteristics

Table 5.1 Absolute Maximum Ratings

Symbol	Parameter	Condition	Rated value	Unit
V_{CC}	Supply Voltage	V_{CC} = AV_{CC}	-0.3 to 6.5	V
AV_{CC}	Analog Supply Voltage	V_{CC} = AV_{CC}	-0.3 to 6.5	V
V_I	Input Voltage		-0.3 to V_{CC}+0.3	V
V_O	Output Voltage		-0.3 to V_{CC}+0.3	V
P_d	Power Dissipation	T_{opr} = 25°C	300	mW
T_{opr}	Operating Ambient Temperature		-20 to 85 / -40 to 85 (D version)	°C
T_{stg}	Storage Temperature		-65 to 150	°C

Table 5.2 Recommended Operating Conditions

Symbol	Parameter		Conditions	Standard			Unit
				Min.	Typ.	Max.	
V_{CC}	Supply Voltage			2.7	–	5.5	V
AV_{CC}	Analog Supply Voltage			–	V_{CC}(3)	–	V
V_{SS}	Supply Voltage			–	0	–	V
AV_{SS}	Analog Supply Voltage			–	0	–	V
V_{IH}	Input “H” Voltage			0.8V_{CC}	–	V_{CC}	V
V_{IL}	Input “L” Voltage			0	–	0.2V_{CC}	V
$I_{OH(sum)}$	Peak Sum Output “H” Current	Sum of All Pins $I_{OH\ (peak)}$		–	–	-60	mA
$I_{OH(peak)}$	Peak Output “H” Current			–	–	-10	mA
$I_{OH(avg)}$	Average Output “H” Current			–	–	-5	mA
$I_{OL(sum)}$	Peak Sum Output “L” Currents	Sum of All Pins $I_{OL\ (peak)}$		–	–	60	mA
$I_{OL(peak)}$	Peak Output “L” Currents	Except P1_0 to P1_3		–	–	10	mA
		P1_0 to P1_3	Drive Capacity HIGH	–	–	30	mA
			Drive Capacity LOW	–	–	10	mA
$I_{OL(avg)}$	Average Output “L” Current	Except P1_0 to P1_3		–	–	5	mA
		P1_0 to P1_3	Drive Capacity HIGH	–	–	15	mA
			Drive Capacity LOW	–	–	5	mA
$f_{(XIN)}$	Main Clock Input Oscillation Frequency		3.0V ≤ V_{CC} ≤ 5.5V	0	–	20	MHz
			2.7V ≤ V_{CC} < 3.0V	0	–	10	MHz

NOTES:
1. V_{CC} = AV_{CC} = 2.7 to 5.5V at T_{opr} = -20 to 85 °C / -40 to 85 °C, unless otherwise specified.
2. The typical values when average output current is 100ms.
3. Hold V_{CC} = AV_{CC}.

Table 5.3 A/D Converter Characteristics

Symbol	Parameter		Conditions	Standard			Unit
				Min.	Typ.	Max.	
–	Resolution		V_{ref} = V_{CC}	–	–	10	Bits
–	Absolute Accuracy	10-Bit Mode	ϕ_{AD} = 10MHz, V_{ref} = V_{CC} = 5.0V	–	–	±3	LSB
		8-Bit Mode	ϕ_{AD} = 10MHz, V_{ref} = V_{CC} = 5.0V	–	–	±2	LSB
		10-Bit Mode	ϕ_{AD} = 10MHz, V_{ref} = V_{CC} = 3.3V(3)	–	–	±5	LSB
		8-Bit Mode	ϕ_{AD} = 10MHz, V_{ref} = V_{CC} = 3.3V(3)	–	–	±2	LSB
R_{ladder}	Resistor Ladder		V_{ref} = V_{CC}	10	–	40	kΩ
t_{conv}	Conversion Time	10-Bit Mode	ϕ_{AD} = 10MHz, V_{ref} = V_{CC} = 5.0V	3.3	–	–	µs
		8-Bit Mode	ϕ_{AD} = 10MHz, V_{ref} = V_{CC} = 5.0V	2.8	–	–	µs
V_{ref}	Reference voltage			–	V_{CC}(4)	–	V
V_{IA}	Analog Input Voltage			0	–	V_{ref}	V
–	A/D Operating Clock Frequency(2)	Without Sample & Hold		0.25	–	10	MHz
		With Sample & Hold		1	–	10	MHz

NOTES:
1. V_{CC} = AV_{CC} = 2.7 to 5.5V at T_{opr} = -20 to 85 °C / -40 to 85 °C, unless otherwise specified.
2. If f1 exceeds 10MHz, divide the f1 and hold A/D operating clock frequency (ϕ_{AD}) 10MHz or below.
3. If the AVcc is less than 4.2V, divide the f1 and hold A/D operating clock frequency (ϕ_{AD}) f1/2 or below.
4. Hold V_{CC} = V_{ref}

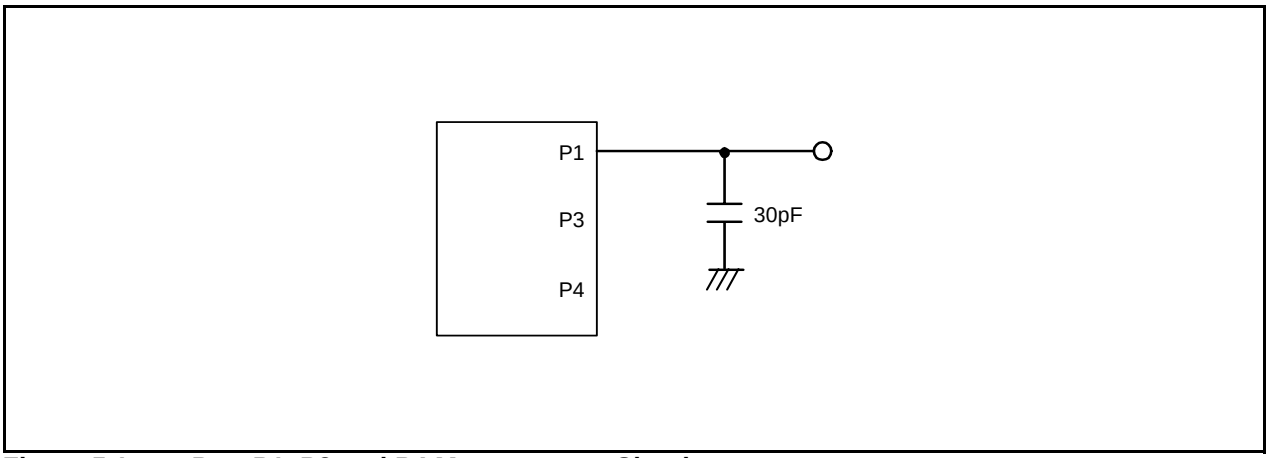


Figure 5.1 Port P1, P3 and P4 Measurement Circuit

Table 5.5 Flash Memory (Data flash Block A, Block B) Electrical Characteristics

Symbol	Parameter	Conditions	Standard			Unit
			Min.	Typ.	Max.	
–	Program/Erase Endurance(2)		10,000(3)	–	–	times
–	Byte Program Time (Program/Erase Endurance ≤ 1,000 Times)	V_{CC} = 5.0 V at T_{opr} = 25 °C	–	50	400	µs
–	Byte Program Time (Program/Erase Endurance > 1,000 Times)	V_{CC} = 5.0 V at T_{opr} = 25 °C	–	65	–	µs
–	Block Erase Time (Program/Erase Endurance ≤ 1,000 Times)	V_{CC} = 5.0 V at T_{opr} = 25 °C	–	0.2	9	s
–	Block Erase Time (Program/Erase Endurance > 1,000 Times)	V_{CC} = 5.0 V at T_{opr} = 25 °C	–	0.3	–	s
$t_{d(SR-ES)}$	Time Delay from Suspend Request until Erase Suspend		–	–	8	ms
–	Erase Suspend Request Interval		10	–	–	ms
–	Program, Erase Voltage		2.7	–	5.5	V
–	Read Voltage		2.7	–	5.5	V
–	Program, Erase Temperature		-20(8)	–	85	°C
–	Data Hold Time(9)	Ambient temperature = 55 °C	20	–	–	year

NOTES:
1. V_{CC} = AVcc = 2.7 to 5.5V at T_{opr} = –20 to 85 °C / –40 to 85 °C, unless otherwise specified.
2. Definition of program and erase
   The program and erase endurance shows an erase endurance for every block.
   If the program and erase endurance is “n” times (n = 100, 10000), “n” times erase can be performed for every block.
   For example, if performing 1-byte write to the distinct addresses on Block A of 1Kbyte block 1,024 times and then erasing that block, program and erase endurance is counted as one time.
   However, do not perform multiple programs to the same address for one time ease.(disable overwriting).
3. Endurace to guarantee all electrical characteristics after program and erase.(1 to “Min.” value can be guaranateed).
4. Standard of Block A and Block B when program and erase endurance exceeds 1,000 times. Byte program time to 1,000 times aer the same as that in program area.
5. In the case of a system to execute multiple programs, perform one erase after programming as reducing effective reprogram endurance not to leave blank area as possible such as programming write addresses in turn . If programming a set of 16 bytes, programming up to 128 sets and then erasing them one time can reduce effective reprogram endurance. Additionally, averaging erase endurance for Block A and B can reduce effective reprogram endurance more. To leave erase endurance for every block as information and determine the restricted endurance are recommended.
6. If error occurs during block erase, attempt to execute the clear status register command, then the block erase command at least three times until the erase error does not occur.
7. Customers desiring Program/Erase failure rate information should contact their Renesas technical support representative.
8. -40 °C for D version.
9. The data hold time incudes time that the power supply is off or the clock is not supplied.

Table 5.8 Reset Circuit Electrical Characteristics (When Using Voltage Monitor 1 Reset)

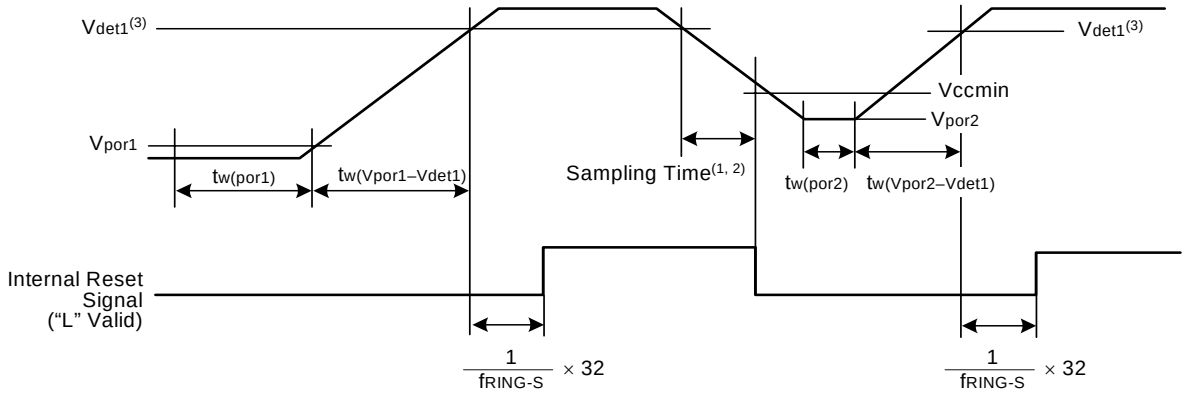
Symbol	Parameter	Condition	Standard			Unit
			Min.	Typ.	Max.	
V_{por2}	Power-On Reset Valid Voltage	-20°C ≤ Topr < 85°C	–	–	V_{det1}	V
$t_{w(Vpor2-Vdet1)}$	Supply Voltage Rising Time When Power-On Reset is Deasserted(1)	-20°C ≤ Topr < 85°C, $t_{w(por2)}$ ≥ 0s(3)	–	–	100	ms

NOTES:
1. This condition is not applicable when using with Vcc ≥ 1.0V.
2. When turning power on after the time to hold the external power below effective voltage (V_{por1}) exceeds10s, refer to **Table 5.9 Reset Circuit Electrical Characteristics (When Not Using Voltage Monitor 1 Reset)**.
3. $t_{w(por2)}$ is time to hold the external power below effective voltage (V_{por2}).

Table 5.9 Reset Circuit Electrical Characteristics (When Not Using Voltage Monitor 1 Reset)

Symbol	Parameter	Condition	Standard			Unit
			Min.	Typ.	Max.	
V_{por1}	Power-On Reset Valid Voltage	-20°C ≤ Topr < 85°C	–	–	0.1	V
$t_{w(Vpor1-Vdet1)}$	Supply Voltage Rising Time When Power-On Reset is Deasserted	0°C ≤ Topr ≤ 85°C, $t_{w(por1)}$ ≥ 10s(2)	–	–	100	ms
$t_{w(Vpor1-Vdet1)}$	Supply Voltage Rising Time When Power-On Reset is Deasserted	-20°C ≤ Topr < 0°C, $t_{w(por1)}$ ≥ 30s(2)	–	–	100	ms
$t_{w(Vpor1-Vdet1)}$	Supply Voltage Rising Time When Power-On Reset is Deasserted	-20°C ≤ Topr < 0°C, $t_{w(por1)}$ ≥ 10s(2)	–	–	1	ms
$t_{w(Vpor1-Vdet1)}$	Supply Voltage Rising Time When Power-On Reset is Deasserted	0°C ≤ Topr ≤ 85°C, $t_{w(por1)}$ ≥ 1s(2)	–	–	0.5	ms

NOTES:
1. When not using the voltage monitor 1 reset, use with Vcc≥ 2.7V.
2. $t_{w(por1)}$ is time to hold the external power below effective voltage (V_{por1}).



NOTES:
1. Hold the voltage of the microcomputer operation voltage range (Vccmin or above) within sampling time.
2. A sampling clock can be selected. Refer to **6. Voltage Detection Circuit** of Hardware Manual for details.
3. V_{det1} indicates the voltage detection level of the voltage detection 1 circuit. Refer to **6. Voltage Detection Circuit** of Hardware Manual for details.

Figure 5.3 Reset Circuit Electrical Characteristics

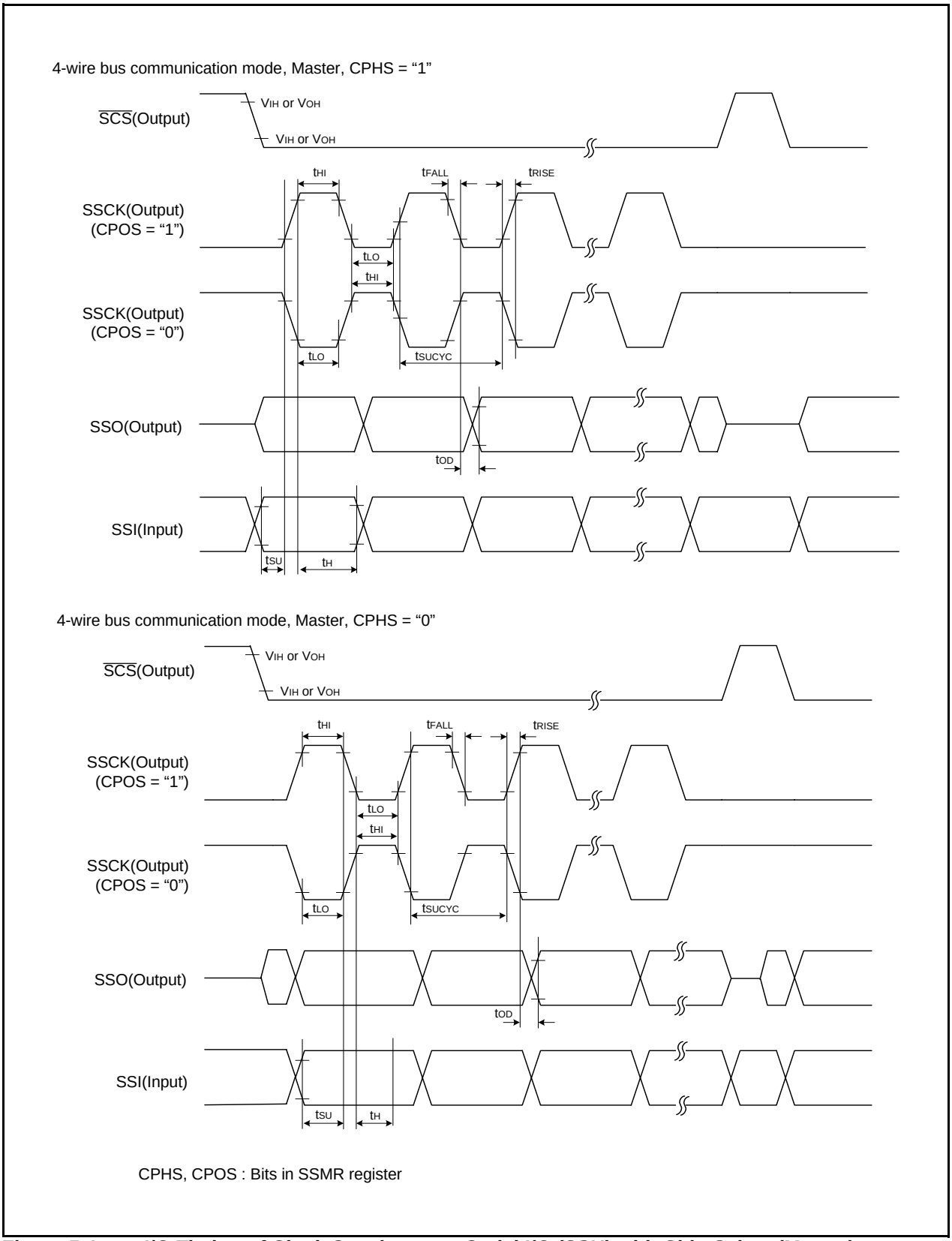


Figure 5.4 I/O Timing of Clock Synchronous Serial I/O (SSU) with Chip Select (Master)

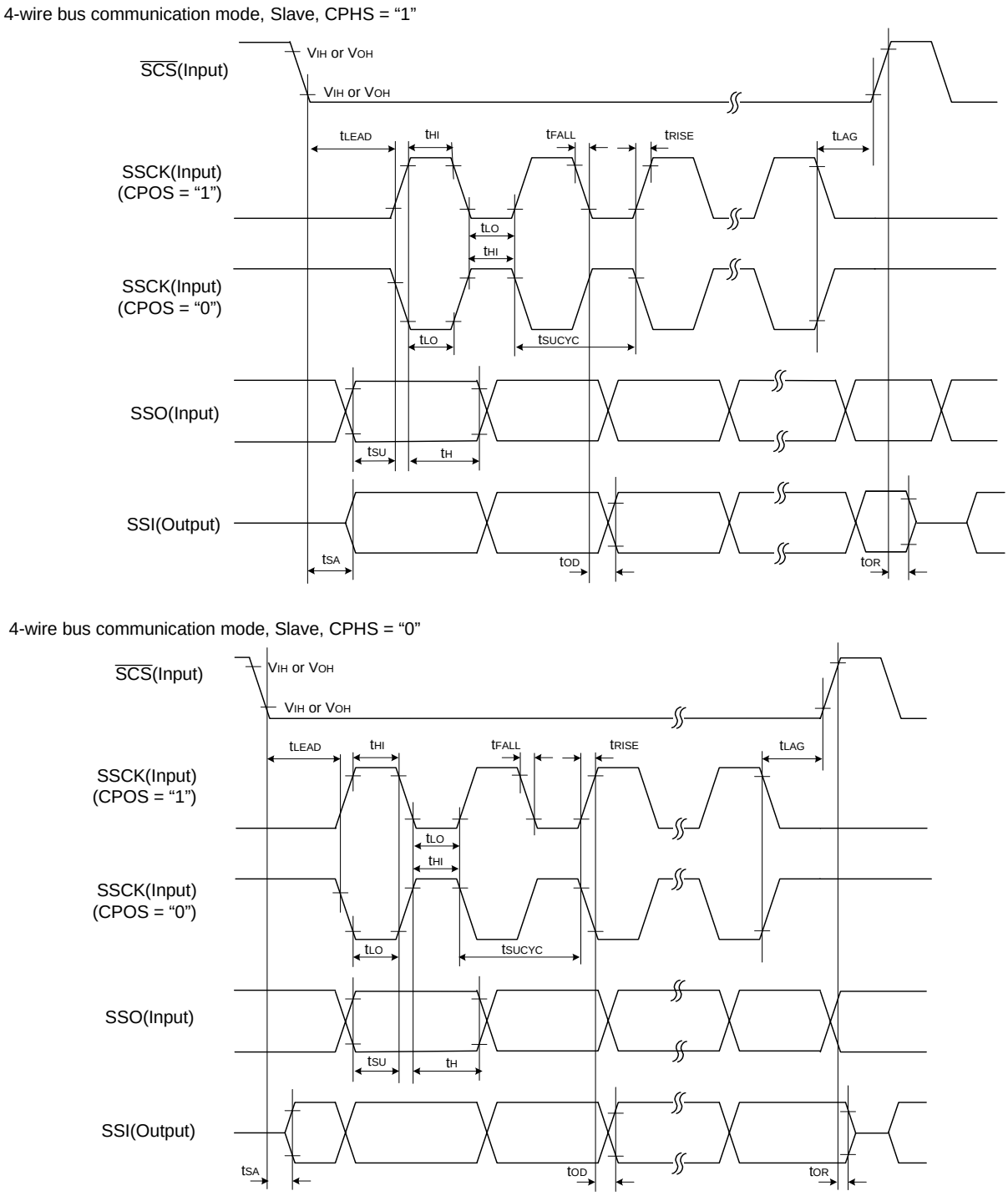


Figure 5.5 I/O Timing of Clock Synchronous Serial I/O (SSU) with Chip Select (Slave)

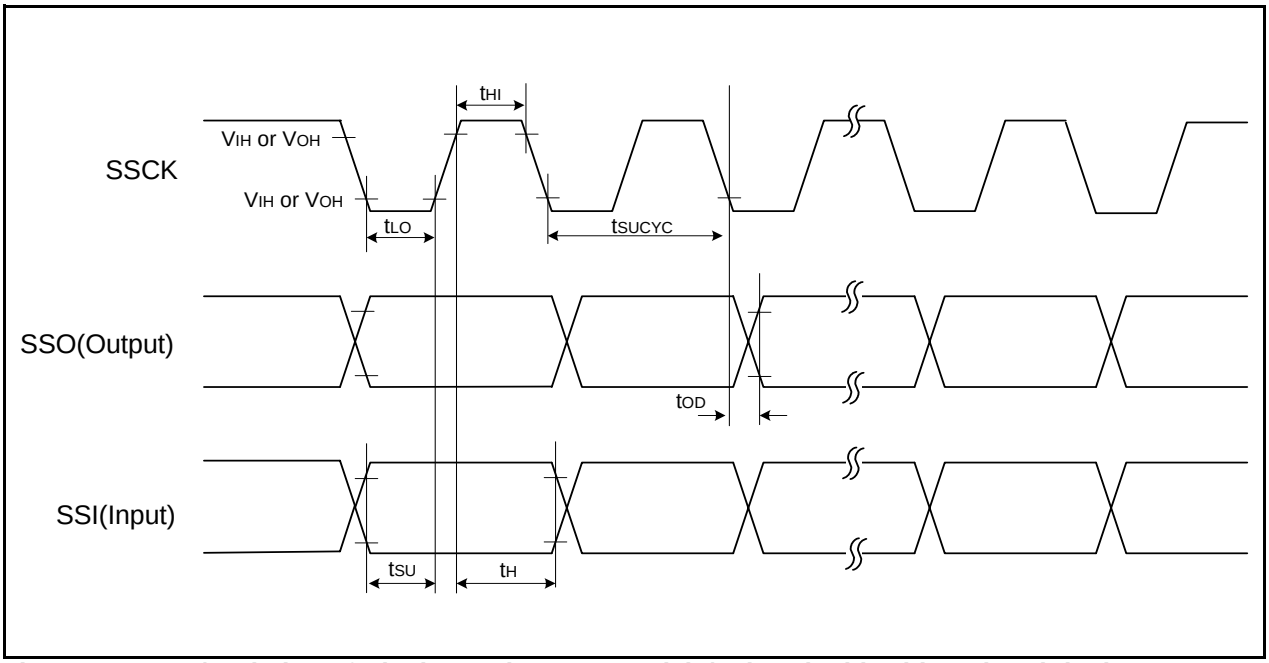


Figure 5.6 I/O Timing of Clock Synchronous Serial I/O (SSU) with Chip Select (Clock Synchronous Communication Mode)

Table 5.13 Electrical Characteristics (1) [Vcc = 5V]

Symbol	Parameter		Condition		Standard			Unit
					Min.	Typ.	Max.	
V_{OH}	Output “H” Voltage	Except X_{OUT}	I_{OH} = -5mA		V_{CC} – 2.0	–	V_{CC}	V
			I_{OH} = -200µA		V_{CC} – 0.3	–	V_{CC}	V
		X_{OUT}	Drive capacity HIGH	I_{OH} = -1mA	V_{CC} – 2.0	–	V_{CC}	V
			Drive capacity LOW	I_{OH} = -500µA	V_{CC} – 2.0	–	V_{CC}	V
V_{OL}	Output “L” Voltage	Except P1_0 to P1_3, X_{OUT}	I_{OL} = 5mA		–	–	2.0	V
			I_{OL} = 200µA		–	–	0.45	V
		P1_0 to P1_3	Drive capacity HIGH	I_{OL} = 15mA	–	–	2.0	V
			Drive capacity LOW	I_{OL} = 5mA	–	–	2.0	V
			Drive capacity LOW	I_{OL} = 200µA	–	–	0.45	V
		X_{OUT}	Drive capacity HIGH	I_{OL} = 1mA	–	–	2.0	V
			Drive capacity LOW	I_{OL} = 500µA	–	–	2.0	V
V_{T+}-V_{T-}	Hysteresis	$\overline{INT0}$, $\overline{INT1}$, $\overline{INT3}$, $\overline{KI0}$, $\overline{KI1}$, $\overline{KI2}$, $\overline{KI3}$, CNTR0, CNTR1, TCIN, RXD0, SSO			0.2	–	1.0	V
		$\overline{RESET}$			0.2	–	2.2	V
I_{IH}	Input “H” current		VI = 5V		–	–	5.0	µA
I_{IL}	Input “L” current		VI = 0V		–	–	-5.0	µA
R_{PULLUP}	Pull-Up Resistance		VI = 0V		30	50	167	kΩ
R_{fXIN}	Feedback Resistance	XIN			–	1.0	–	MΩ
f_{RING-S}	Low-Speed On-Chip Oscillator Frequency				40	125	250	kHz
V_{RAM}	RAM Hold Voltage		During stop mode		2.0	–	–	V

NOTES:
1. V_{CC} = AV_{CC} = 4.2 to 5.5V at T_{opr} = -20 to 85 °C / -40 to 85 °C, f(XIN)=20MHz, unless otherwise specified.

Table 5.21 Electrical Characteristics (4) [Vcc = 3V] (Topr = -40 to 85 °C, unless otherwise specified.)

Symbol	Parameter	Condition		Standard			Unit
				Min.	Typ.	Max.	
Icc	Power Supply Current (Vcc=2.7 to 3.3V) In single-chip mode, the output pins are open and other pins are Vss	High-Speed Mode	XIN = 20MHz (square wave) High-speed on-chip oscillator off Low-speed on-chip oscillator on=125kHz No division	–	8	13	mA
			XIN = 16MHz (square wave) High-speed on-chip oscillator off Low-speed on-chip oscillator on=125kHz No division	–	7	12	mA
			XIN = 10MHz (square wave) High-speed on-chip oscillator off Low-speed on-chip oscillator on=125kHz No division	–	5	–	mA
		Medium-Speed Mode	XIN = 20MHz (square wave) High-speed on-chip oscillator off Low-speed on-chip oscillator on=125kHz Divide-by-8	–	3	–	mA
			XIN = 16MHz (square wave) High-speed on-chip oscillator off Low-speed on-chip oscillator on=125kHz Divide-by-8	–	2.5	–	mA
			XIN = 10MHz (square wave) High-speed on-chip oscillator off Low-speed on-chip oscillator on=125kHz Divide-by-8	–	1.6	–	mA
		High-Speed On-Chip Oscillator Mode	Main clock off High-speed on-chip oscillator on=8MHz Low-speed on-chip oscillator on=125kHz No division	–	3.5	7.5	mA
			Main clock off High-speed on-chip oscillator on=8MHz Low-speed on-chip oscillator on=125kHz Divide-by-8	–	1.5	–	mA
		Low-Speed On-Chip Oscillator Mode	Main clock off High-speed on-chip oscillator off Low-speed on-chip oscillator on=125kHz Divide-by-8	–	420	800	µA
		Wait Mode	Main clock off High-speed on-chip oscillator off Low-speed on-chip oscillator on=125kHz While a WAIT instruction is executed Peripheral clock operation VCA26 = VCA27 = 0	–	37	74	µA
		Wait Mode	Main clock off High-speed on-chip oscillator off Low-speed on-chip oscillator on=125kHz While a WAIT instruction is executed Peripheral clock off VCA26 = VCA27 = 0	–	35	70	µA
		Stop Mode	Main clock off, Topr = 25 °C High-speed on-chip oscillator off Low-speed on-chip oscillator off CM10 = 1 Peripheral clock off VCA26 = VCA27 = 0	–	0.7	3.0	µA

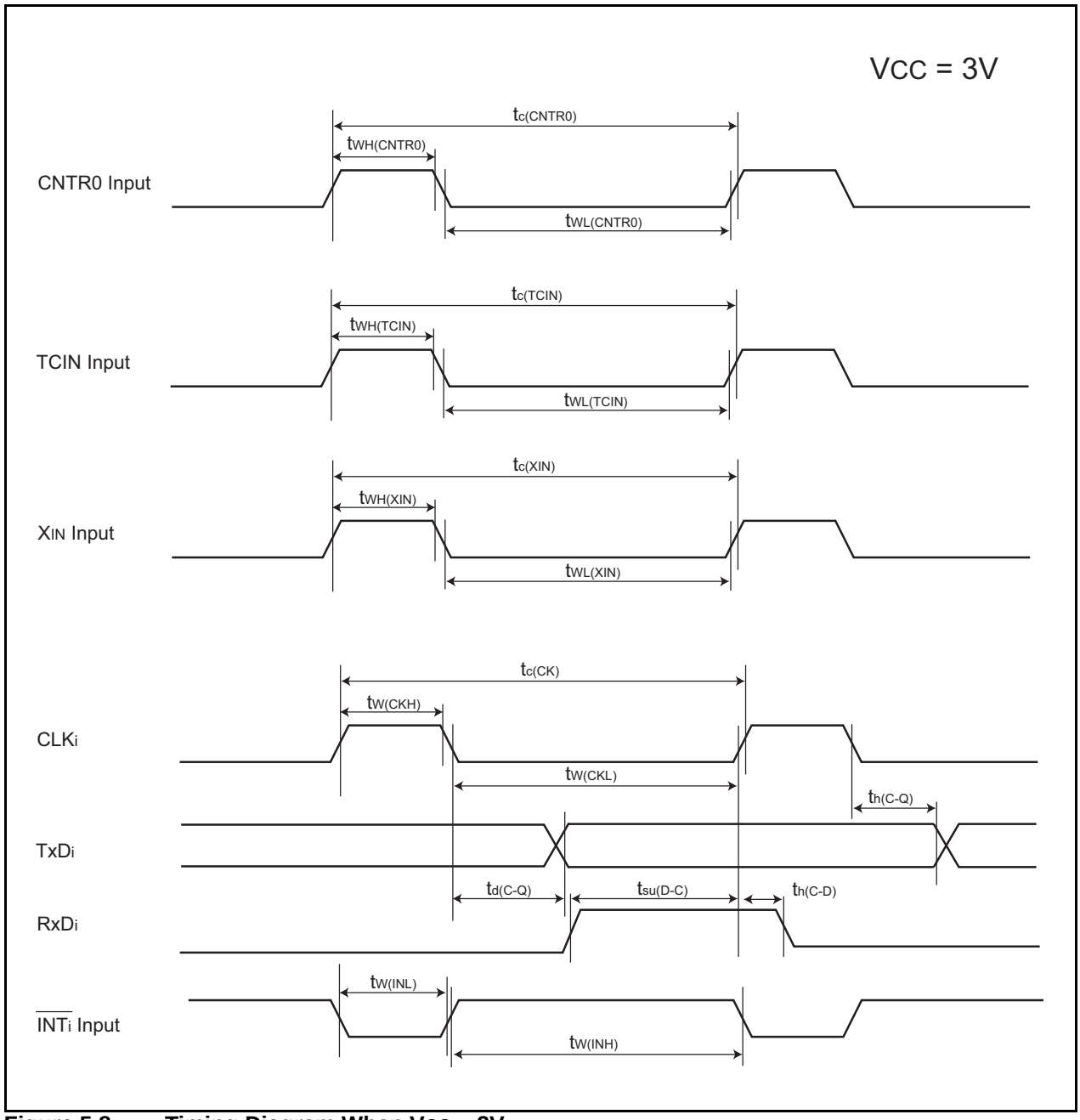
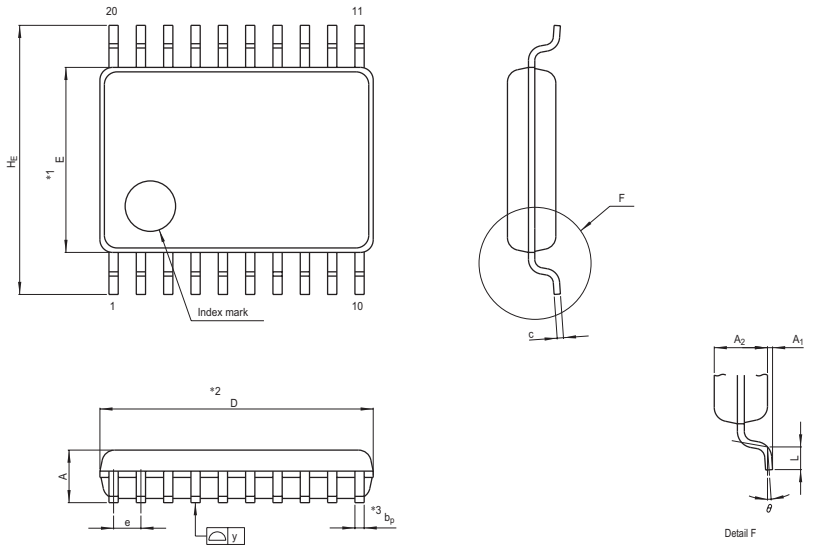


Figure 5.8 Timing Diagram When Vcc = 3V

Package Dimensions

JEITA Package Code	RENESAS Code	Previous Code	MASS[Typ.]
P-LSSOP20-4.4x6.5-0.65	PLSP0020JB-A	20P2F-A	0.1g



NOTE)
1. DIMENSIONS "*1" AND "*2" DO NOT INCLUDE MOLD FLASH.
2. DIMENSION "*3" DOES NOT INCLUDE TRIM OFFSET.

Reference Symbol	Dimension in Millimeters		
	Min	Nom	Max
D	6.4	6.5	6.6
E	4.3	4.4	4.5
A_2	——	1.15	——
A	——	——	1.45
A_1	0	0.1	0.2
b_p	0.17	0.22	0.32
c	0.13	0.15	0.2
θ	0°	——	10°
H_E	6.2	6.4	6.6
e	0.53	0.65	0.77
y	——	——	0.10
L	0.3	0.5	0.7

REVISION HISTORY	R8C/14 Group, R8C/15 Group Datasheet

Rev.	Date	Description	
		Page	Summary
0.10	Sep 06, 2004	–	First Edition issued
1.00	Feb 25, 2005	2-3	Tables 1.1 and 1.2 revised
		5	Table 1.3 and figure 1.2 revised
		6	Table 1.4 and figure 1.3 revised
		7-8	Figures 1.4 and 1.5 revised
		16	Table 4.1 revised: - 000Fh: 000XXXXXb → 00011111b - 0036h: 00001000b → 0000X000b and 01001001b → 0100X001b
		18	Tabel 4.3 revised: - 009Ch: FFh → 00h; NOTES2 added - 009Dh: FFh → 00h - 00BCh: 10000000b → 00h
		21	Table 5.3 revised
		22	Tables 5.4 and 5.5 revised
		24	Tables 5.8 and 5.9 revised
		25	Table 5.11 revised; Table 5.12 added
		26-28	Figures 5.4 to 5.6 added
		29	Table 5.13 revised
		30	Table 5.14 revised
		31, 35	Table 5.16 and 5.23 revised: Table title “INT2” → “INT1”
		33	Table 5.20 revised; NOTE revised
		34	Table 5.21 revised
		37	Package Dimensions revised
1.10	Jul 07, 2005	5, 6	Tables 1.3 and 1.4 revised
		16	Table 4.1 revised: - 0009h: XXXXXX00b → 00h - 000Ah: 00XXX000b → 00h - 001Eh: XXXXX000b → 00h
		22	Table 5.5 revised; NOTE revised
		26	Figure 5.4 revised
		27	Figure 5.5 revised
		29	Table 5.13 revised
		33	Table 5.20 revised
2.00	Jan 30, 2006	1	1. Overview; “20-pin plastic molded LSSOP or SDIP” → “20-pin plastic molded LSSOP” revised
		2	Table 1.1 Performance Outline of the R8C/14 Group; Package: “20-pin plastic molded SDIP” deleted
		3	Table 1.2 Performance Outline of the R8C/15 Group; Package: “20-pin plastic molded SDIP” deleted, Flash Memory: (Data area) → (Data flash) (Program area) → (Program ROM) revised
		4	Figure 1.1 Block Diagram; “Peripheral Function” added, “System Clock Generation” → “System Clock Generator” revised
		5, 6	Table 1.3 Product Information of R8C/14 Group, Table 1.4 Product Information of R8C/15 Group; revised. Figure 1.2 Part Number, Memory Size and Package of R8C/14 Group, Figure 1.3 Part Number, Memory Size and Package of R8C/15 Group; Package type: “DD : PRDP0020BA-A” deleted